

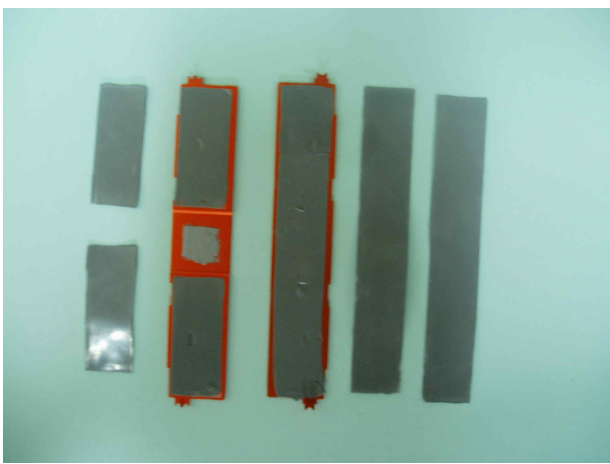
# HEATFLOW-SIL

# LY-TCS 8050

HEATFLOW-SIL, LY-TCS 8050 is a medium conformable, medium modulus silicone polymer filled with special conductive filler that allows the pad to fill in air voids between PC boards and heat sink or metal chassis (heat spreader) with rough surface and high stack-up tolerances.

HEATFLOW-SIL, LY-TCS 8050 is specially designed as high thermally conductive interface materials and flame retardant UL94V-O level together with good electrical properties.

HEATFLOW-SIL, LY-TCS 8050 is supplied with self-stick of one or both sides, and supplied on a reinforcing carrier (glass fiber or thin PET film) for easy material handling and enhanced puncture, shear and tear resistance.



## Special feature

- Medium soft and flexible elastic silicone conformable pad
- Any thickness are available
- Medium thermally conductivity, 5.0 W/mK
- Excellent flame retardant as UL94V-O level
- Easy for cutting and mounting
- Excellent electrical insulation properties

## Application

- Areas where heat needs to be transferred away to the frame chassis or other type of heat spreader
- Computer and peripherals
- Telecommunication
- Between a CD ROM and a heat spreader
- Between a semiconductor and heat sink
- Replacement for messy grease
- RDRAM, DDR SDRAM Memory Modules

## Products supply

HEATFLOW-SIL LY-TCS 8050 is available in standard size and custom width and length  
Standard Size (mm) : 200×200, 210×300

**HEATFLOW-SIL****LY-TCS 8050**

## PROPERTIES

Properties		TCS-8050	Test Method
Thickness	(mm)	0.5~10.0	ASTM D 374
Color		Gray	Visual
Reinforcement		PET	*Option
Hardness	(Shore 00)	75	ASTM D 2240
Specific Gravity	(g/cm <sup>3</sup> )	3.1 ~ 3.3	ASTM D 792
Continue Use	(°C)	-40 ~ +100	
Thermal Conductivity	10psi (w/m.K)	5.0	ASTM D 5470
Dielectric Constant		5.1	ASTM D 150
Dielectric Breakdown	kV AC	>8	ASTM D 149
Volume Resistivity	ohm Meter	>10 <sup>12</sup>	ASTM D 257